

ON Semiconductor®

FDPF7N50U

N-Channel UniFETTM Ultra FRFETTM MOSFET 500 V, 5 A, 1.5 Ω

Features

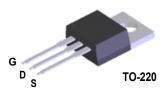
- $R_{DS(on)}$ = 1.5 Ω (Max.) @ V_{GS} = 10 V, I_D = 2.5 A
- Low Gate Charge (Typ.12.8 nC)
- Low C_{rss} (Typ. 9 pF)
- · 100% Avalanche Tested
- · Improved dv/dt Capability

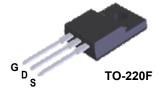
Applications

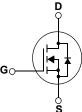
- LCD/LED TV
- · Lighting
- · Uninterruptible Power Supply
- AC-DC Power Supply

Description

UniFETTM MOSFET is ON Semiconductor's high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. UniFET Ultra FRFETTM MOSFET has much superior body diode reverse recovery performance. Its t_{rr} is less than 50nsec and the reverse dv/dt immunity is 20V/nsec while normal planar MOSFETs have over 200nsec and 4.5V/nsec respectively. Therefore UniFET Ultra FRFET MOSFET can remove additional component and improve system reliability in certain applications that require performance improvement of the MOSFET's body diode. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.







Absolute Maximum Ratings

				ა		
Symbol	Parameter Drain-Source Voltage			FDPF7N50U	Unit V	
V _{DSS}				500		
I _D	Drain Current	- Continuous (T _C = 25°C) - Continuous (T _C = 100°C)		5 * 3.0 *	A A	
I _{DM}	Drain Current	- Pulsed	(Note 1)	20 *	А	
V _{GSS}	Gate-Source voltage			±30	V	
E _{AS}	Single Pulsed Avalanche Energy		(Note 2)	125	mJ	
I _{AR}	Avalanche Current		(Note 1)	5	А	
E _{AR}	Repetitive Avalanche Energy		(Note 1)	8.9	mJ	
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	20	V/ns	
P_{D}	Power Dissipation	(T _C = 25°C) - Derate above 25°C		31.3 0.25	W W/°C	
T _{J,} T _{STG}	Operating and Storage Temperature Range			-55 to +150	°C	
T _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		9,	300	°C	

^{*} Drain current limited by maximum junction temperature.

Thermal Characteristics

Symbol	Parameter	FDPF7N50U	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	4.0	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5		

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDPF7N50U	FDPF7N50U	TO-220F		-	50

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Conditions	Min.	Тур.	Max	Unit
Off Charac	teristics			ı		
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	500			V
$\Delta BV_{DSS} \ \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25°C	-	0.5		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 500V, V _{GS} = 0V V _{DS} = 400V, T _C = 125°C			25 250	μ Α μ Α
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30V, V _{DS} = 0V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30V, V _{DS} = 0V			-100	nA
On Charac	teristics	•		•	•	•
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D = 2.5A		1.2	1.5	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40V, I _D = 2.5A		2.5		S
Dynamic C	: haracteristics					
C _{iss}	Input Capacitance	V _{DS} = 25V, V _{GS} = 0V,		720	940	pF
C _{oss}	Output Capacitance	f = 1.0MHz		95	190	pF
C _{rss}	Reverse Transfer Capacitance			9	13.5	pF
Switching	Characteristics					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 250V, I _D = 5A		6	20	ns
t _r	Turn-On Rise Time	$R_G = 25\Omega$		55	120	ns
t _{d(off)}	Turn-Off Delay Time			25	60	ns
t _f	Turn-Off Fall Time	(Note 4)		35	80	ns
Qg	Total Gate Charge	V _{DS} = 400V, I _D = 5A		12.8	16.6	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10V		3.7		nC
Q_{gd}	Gate-Drain Charge	(Note 4)		5.8		nC
Drain-Sour	ce Diode Characteristics and Maximur	n Ratings		I		
I _S	Maximum Continuous Drain-Source Diode Forward Current				5	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				20	Α
V_{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0V, I _S = 5A			1.6	٧
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S = 5A		40		ns
Q _{rr}	Reverse Recovery Charge	dI _F /dt =100A/μs		0.04		μС

NOTES

- ${\bf 1.}\ {\bf Repetitive}\ {\bf Rating:}\ {\bf Pulse}\ {\bf width}\ {\bf limited}\ {\bf by}\ {\bf maximum}\ {\bf junction}\ {\bf temperature}$
- 2. I $_{AS}$ = 5A, V $_{DD}$ = 50V, L=10mH, R $_{G}$ = 25 Ω , Starting T $_{J}$ = 25 $^{\circ}$ C
- 3. $I_{SD} \le$ 5A, di/dt \le 200A/ μ s, $V_{DD} \le$ BV $_{DSS}$, Starting T_J = 25°C
- 4. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

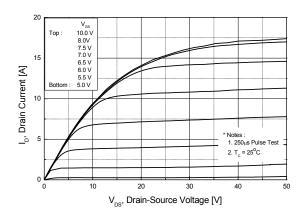


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

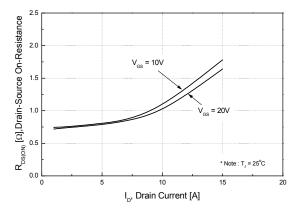


Figure 5. Capacitance Characteristics

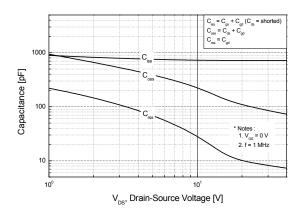


Figure 2. Transfer Characteristics

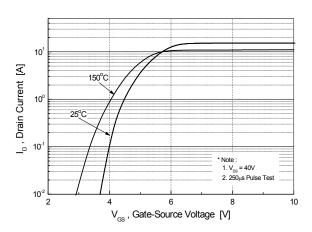


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

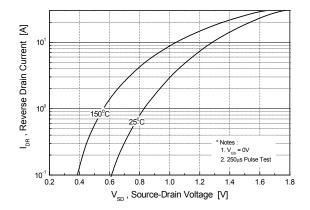
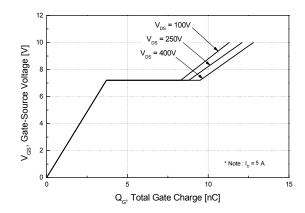


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

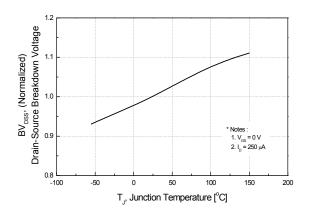


Figure 8. Maximum Drain Current Vs. Case Temperature

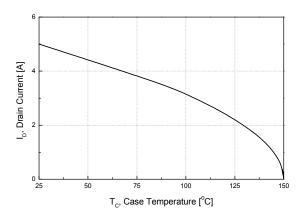


Figure 9. Maximum Safe Operating Area - FDPF7N50U

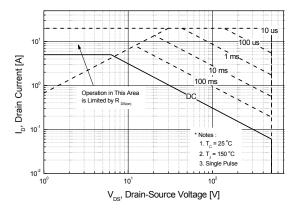
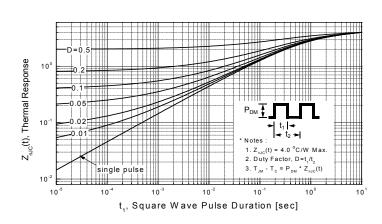
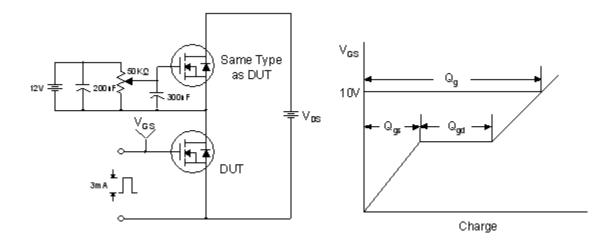


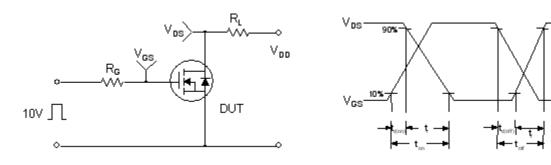
Figure 10. Transient Thermal Response Curve



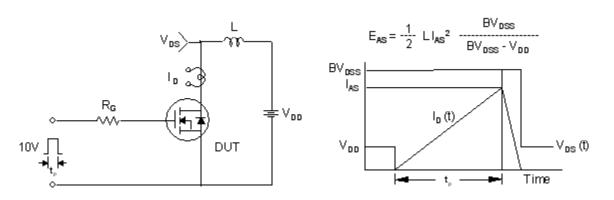
Gate Charge Test Circuit & Waveform



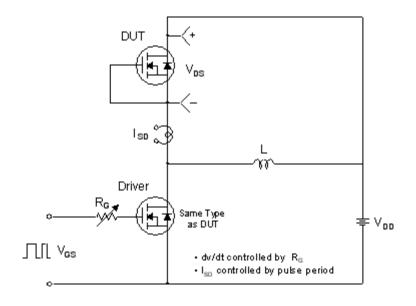
Resistive Switching Test Circuit & Waveforms

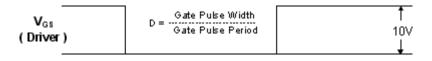


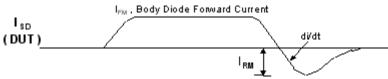
Unclamped Inductive Switching Test Circuit & Waveforms



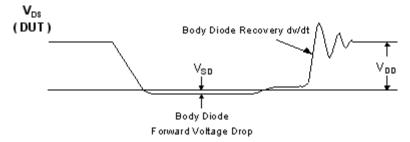
Peak Diode Recovery dv/dt Test Circuit & Waveforms







Body Diode Reverse Current



Mechanical Dimensions TO-220M03 2.742.34 10.36 Α 9.96 Ø 3.28 7.00 3.40 3.08 0.70 3.20 SEE NOTE "F" SEE NOTE "F" 6.88 6.48 \pm 1 X 45° 16.07 15.67 16.00 15.60 (3.23) B 3 1.47 2.96 1.24 2.14 2.56 0.90 10.05 0.70 9.45 \oplus 0.50 M A 30° 0.45 0.60 0.25 0.45 2.54 2.54 NOTES: A. EXCEPT WHERE NOTED CONFORMS TO EIAJ SC91A. D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND THE BAR AS DEPARTMENT. 4.90 <u>/</u>B\ 4.50 E. DIMENSION AND TOLERANCE AS PER ASME Y14.5-1994 F. OPTION 1 - WITH SUPPORT PIN HOLE. OPTION 2 - NO SUPPORT PIN HOLE. G. DRAWING FILE NAME: TO220M03REV3 **Dimensions in Millimeters**

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